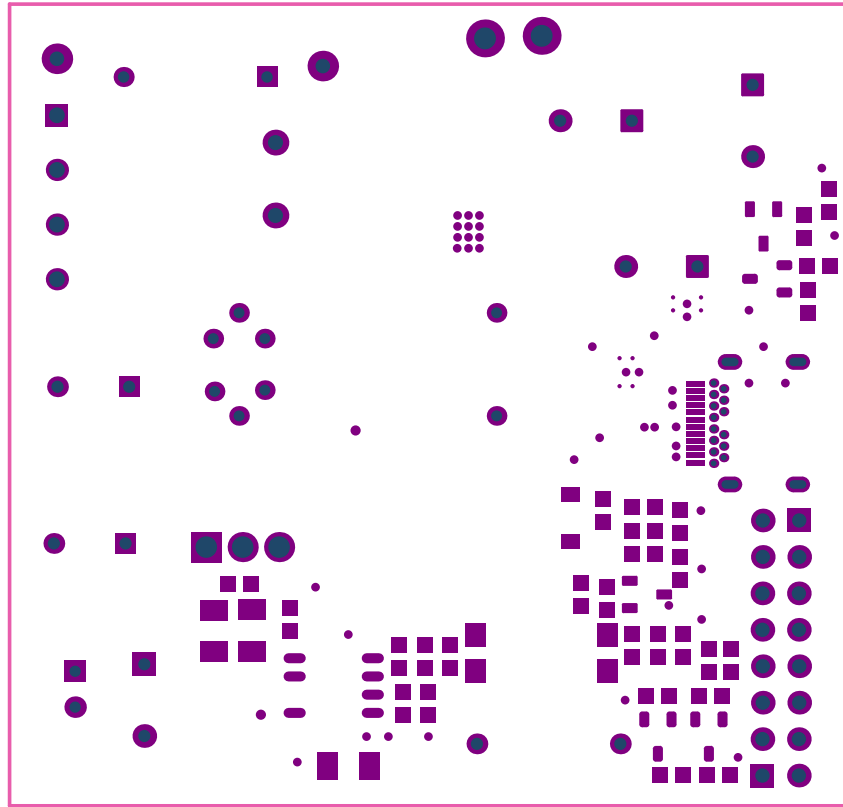
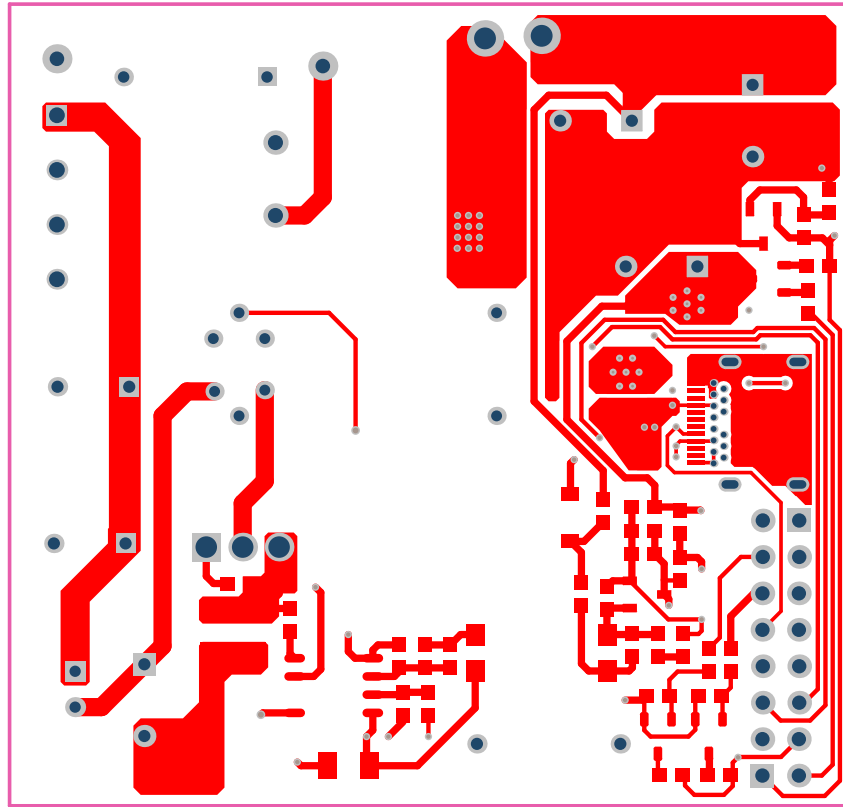


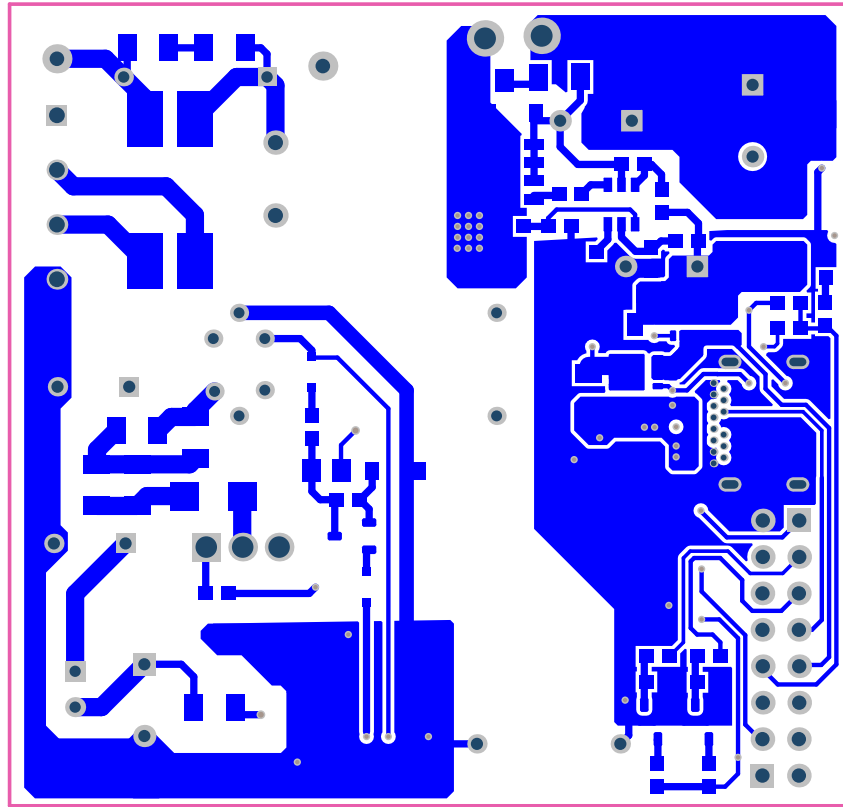
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40183	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 3/7/2018	12:45:58 PM	TEXAS INSTRUMENTS



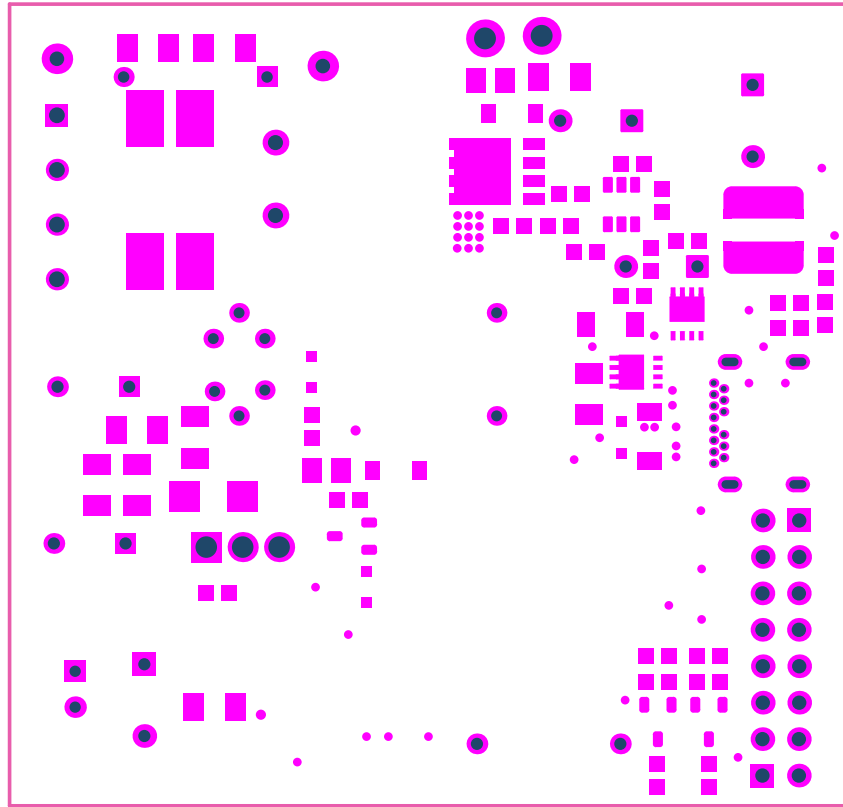
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40183	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 3/7/2018 12:45:59 PM	TEXAS INSTRUMENTS	



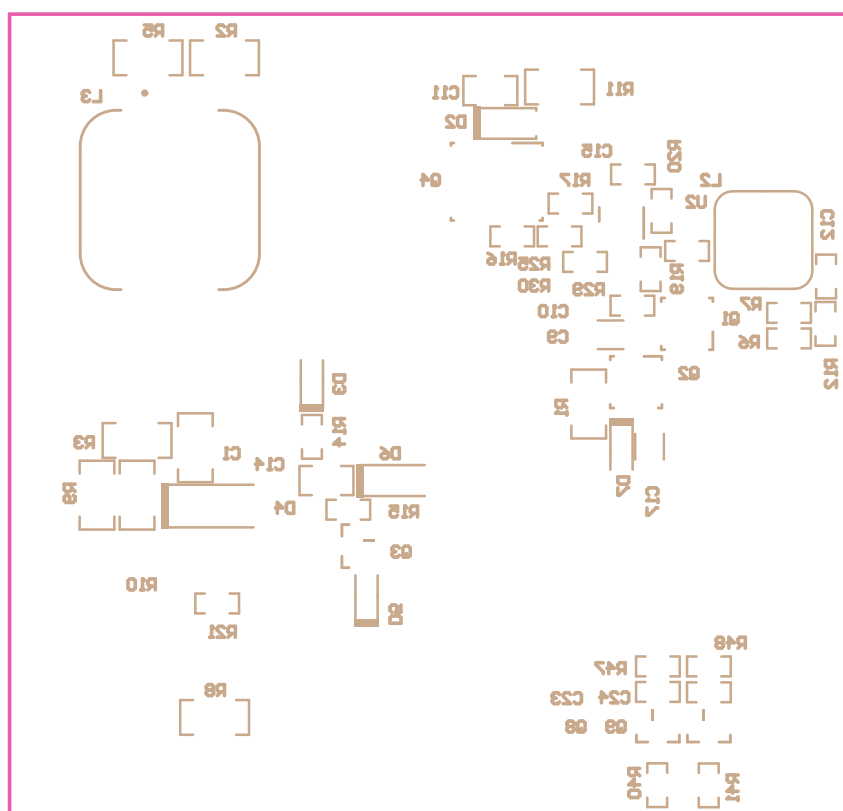
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40183	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 3/7/2018	12:46:00 PM	TEXAS INSTRUMENTS



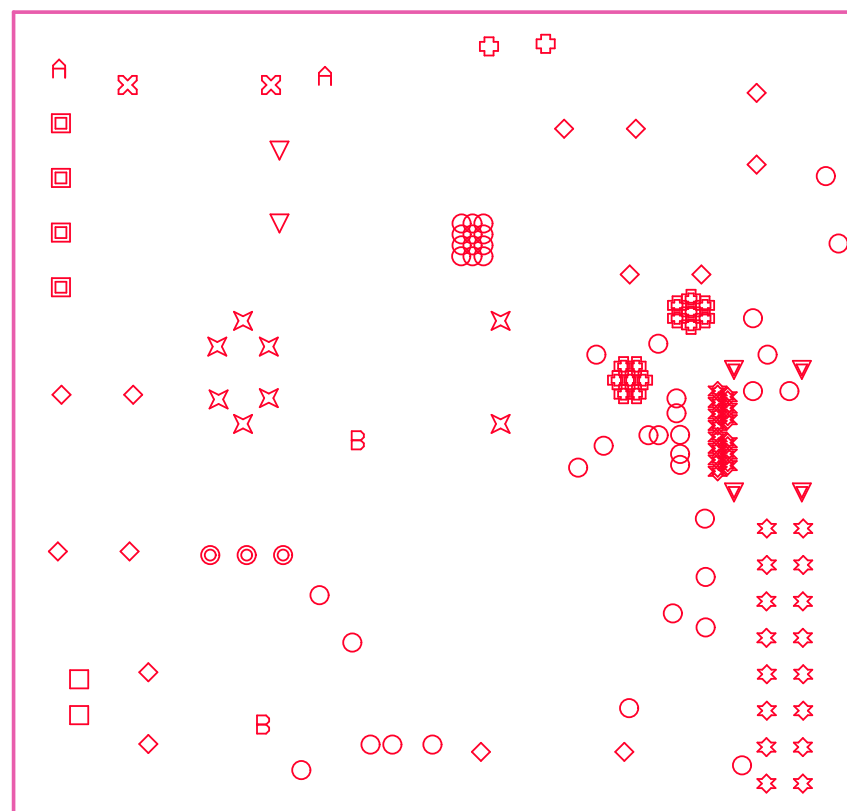
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40183	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 3/7/2018 12:46:01 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40183	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/7/2018 12:46:02 PM	TEXAS INSTRUMENTS	



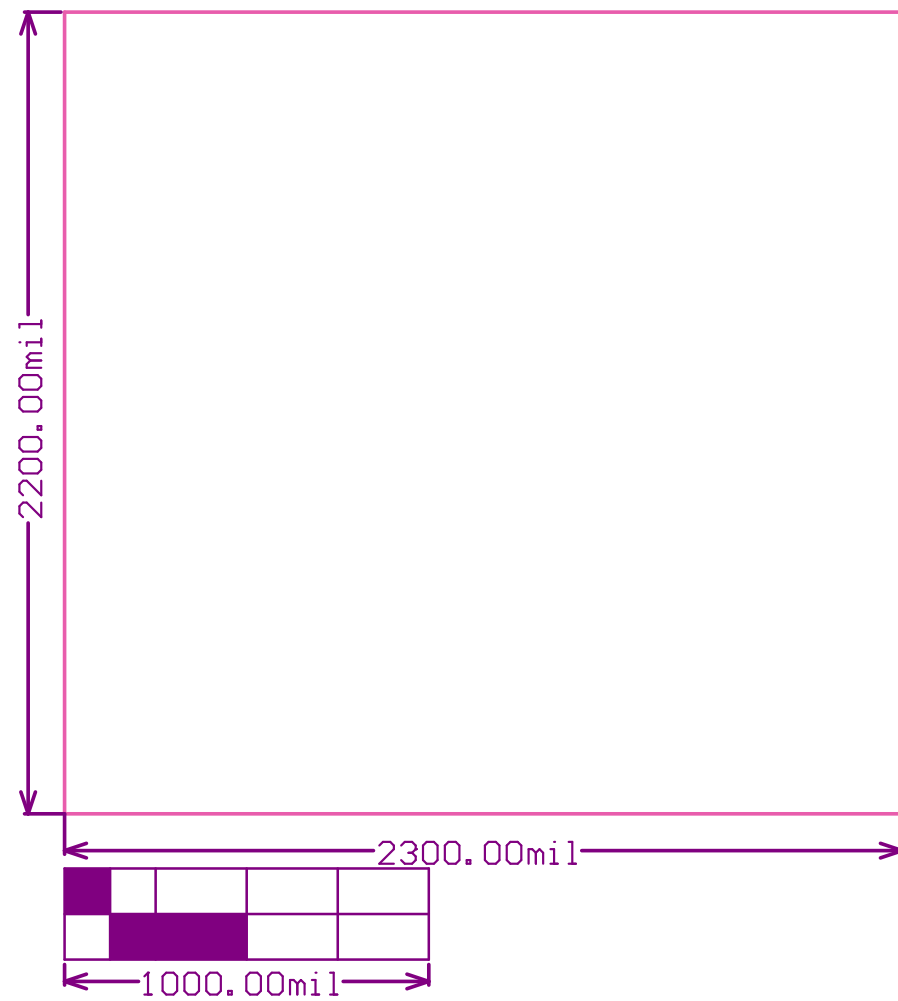
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40183	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 3/7/2018 12:46:04 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊕	14	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	41	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
☆	14	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	
B	2	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	8	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
□	2	31.00mil (0.787mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
◇	14	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
☆	16	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⌒	2	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	3	59.06mil (1.500mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	60.00mil (1.524mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	23.62mil (0.600mm)	PTH	Slot	Top Layer - Bottom Layer	
	130 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40183	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 3/7/2018	12:46:05 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40183	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 3/7/2018	12:46:06 PM	TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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